



PTP81608T08

SMD Type Phototransistor

Features

- Small double-end package
- High photo sensitivity
- High reliability
- Spectral range of sensitivity: 400-1100nm
- Fast Response time
- RoHS compliance

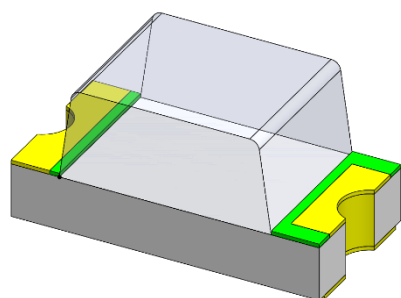
Applications

- Infrared sensor
- Infrared Touch Panel Solutions

Description

The PTP81608T08 is silicon NPN Phototransistor. The device has wide spectral sensitivity range from 400 to 1100nm.

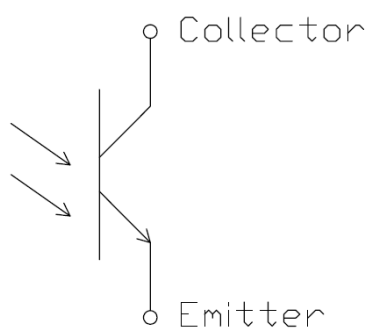
Package Outline



Emitter

Collector

Schematic



**Absolute Maximum Rating at 25°C**

Symbol	Parameters	Ratings	Units	Notes
I _C	Collector Current	20	mA	
B _{VCE0}	Collector-Emitter Voltage	35	V	1
B _{VE0}	Emitter-Collector Voltage	5	V	2
T _{opr}	Operating Temperature	-40 ~ +85	°C	
T _{stg}	Storage Temperature	-40 ~ +100	°C	
T _{sol}	Soldering Temperature	260	°C	3
P _{to}	Total Power Dissipation	150	mW	

Optical Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
λ	Spectral Bandwidth	-	400	-	1100	nm	
λ _P	Peak Sensitivity	-	-	820	-	nm	
θ _{1/2}	View Angle	V _{CE} =5V	-	±55	-	deg	

Electrical Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
I _{CEO}	Dark Current	E _e =0mW /cm ² V _{CE} =20V	-	-	100	nA	
V _{CE(sat)}	Collector-Emitter Saturation Voltage	E _e =1mW /cm ² I _C =0.3mA	-	-	0.4	V	
I _C	Collector Light Current	E _e =1mW /cm ² λ _P =940nm, V _{CE} =5V	0.30	0.60	-	mA	4
C _T	Terminal Capacitance	E _e =0mW /cm ² f=1MHz, V _{CE} =5V	-	2.35	-	pF	



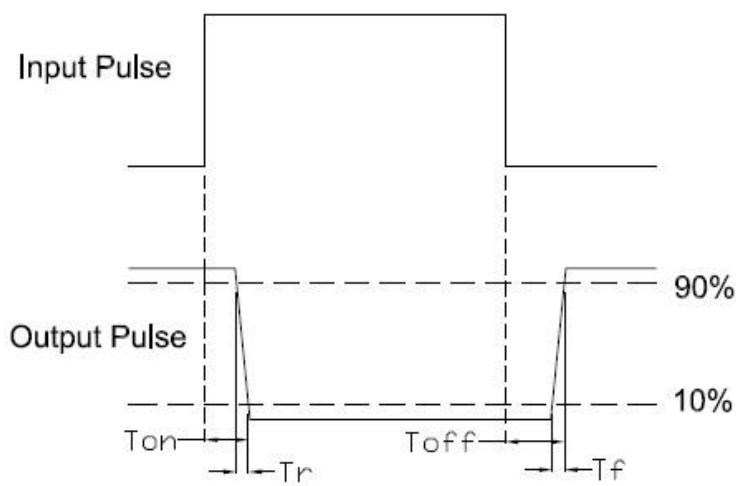
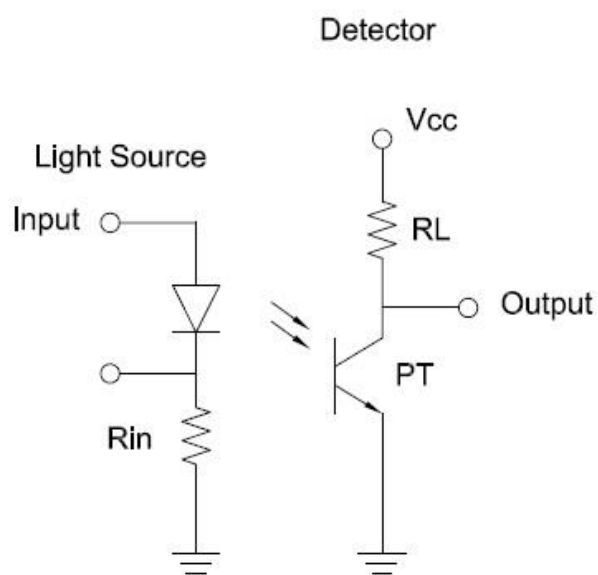
Switching Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
t_r	Rise Time	$V_{ce} = 5V, R_L = 100\Omega$ $I_C = 1.0mA$	-	4	-	μs	5
t_f	Fall Time		-	5.2	-		
t_{on}	Turn on Delay Time		-	7.3	-		
t_{off}	Turn off Delay Time		-	6.1	-		

Notes:

- 1 : Test conditions : $I_C = 100\mu A, E_e = 0mW/cm^2$.
- 2 : Test conditions : $I_E = 100\mu A, E_e = 0mW/cm^2$.
- 3 : Soldering time ≤ 5 seconds.
- 4 : I_C Bin Rank :

5 : Test circuit:



Switching Time



Typical Characteristic Curves

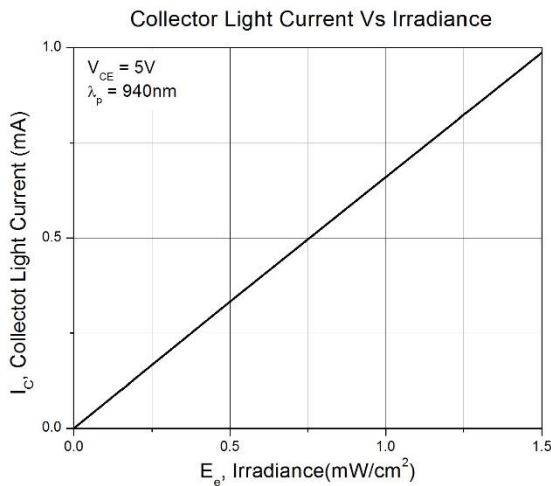


Figure 1

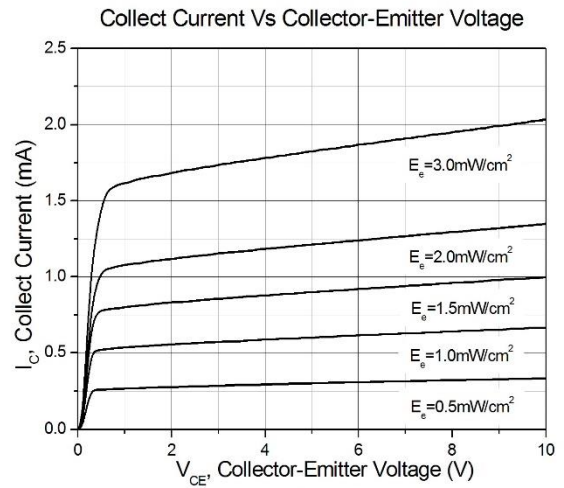


Figure 2

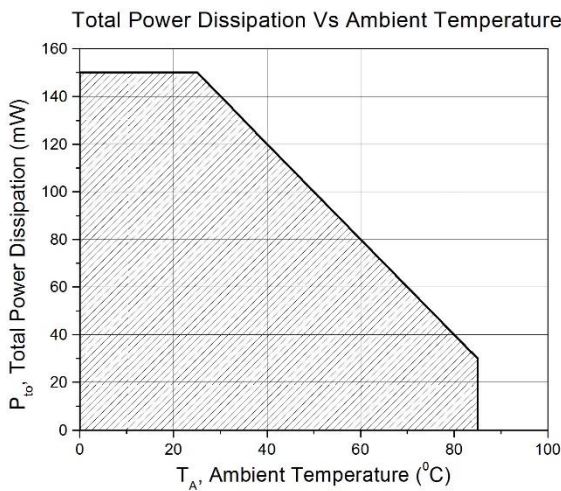


Figure 3

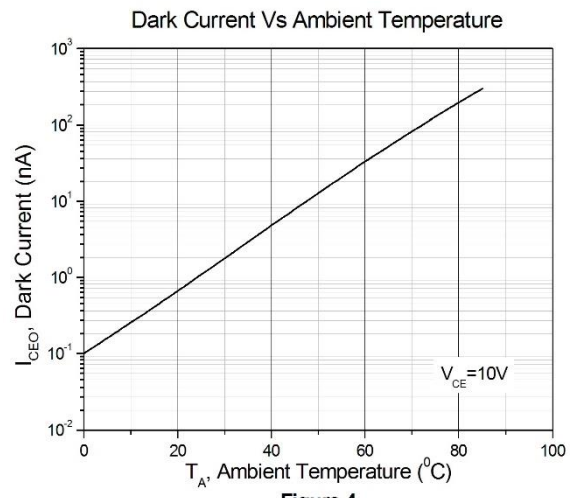


Figure 4

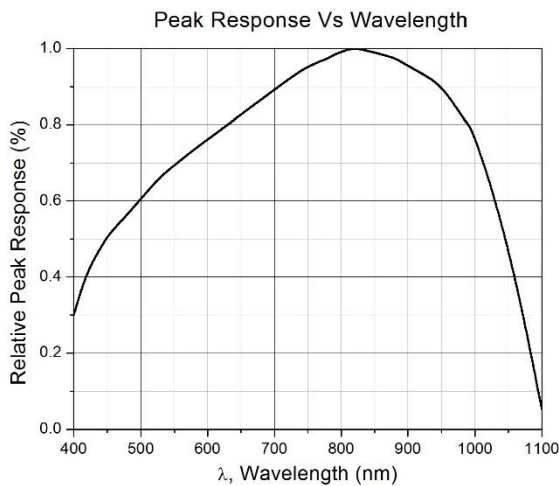


Figure 5

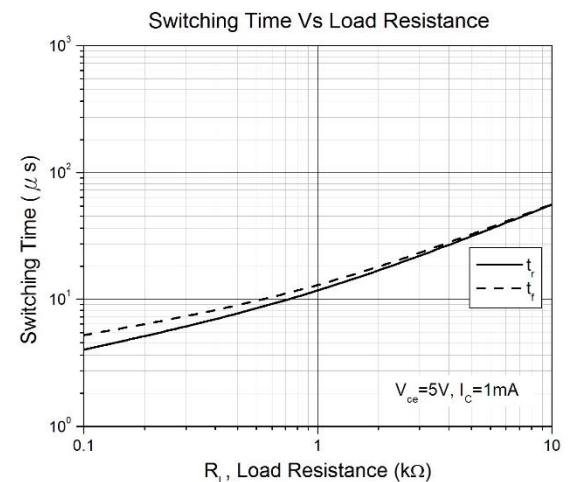


Figure 6



Typical Characteristic Curves

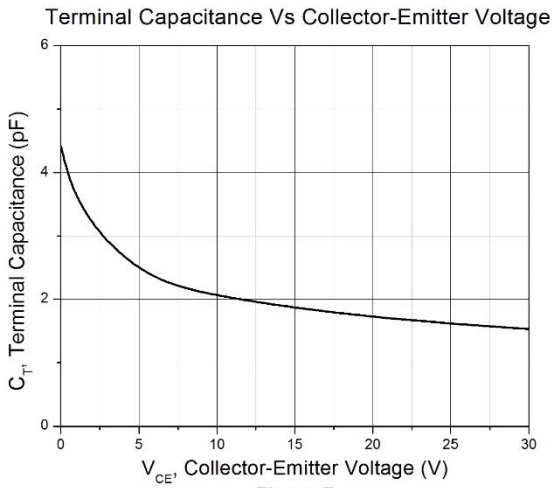


Figure 7

Angular Displacement

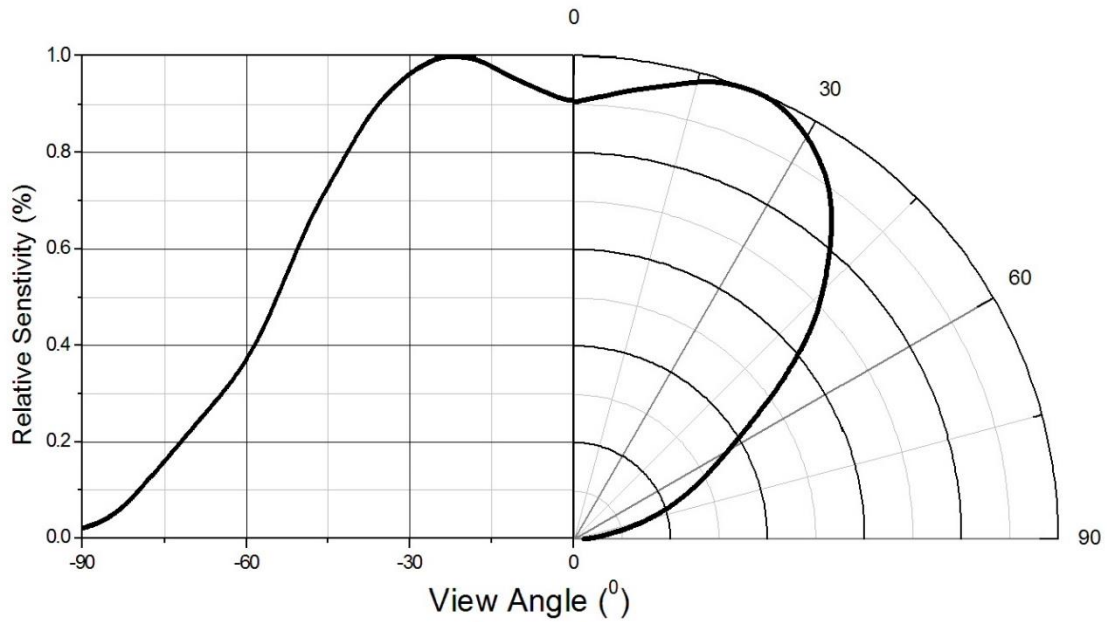
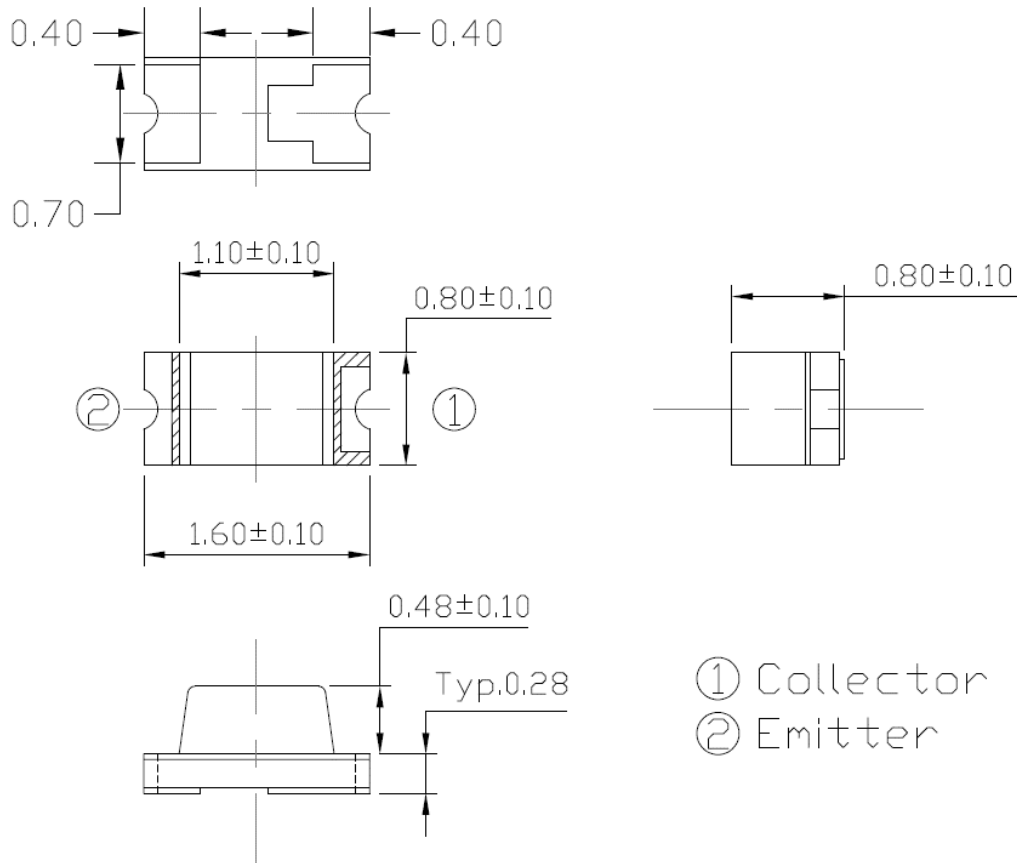


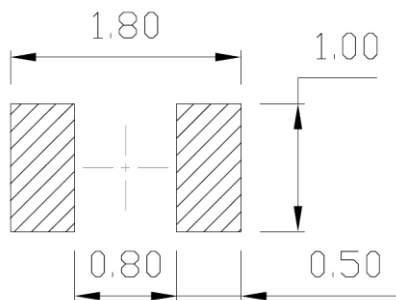
Figure 8



Package Dimension *All dimensions are in mm, unless otherwise stated*



Recommended Soldering Mask *All dimensions are in mm, unless otherwise stated*

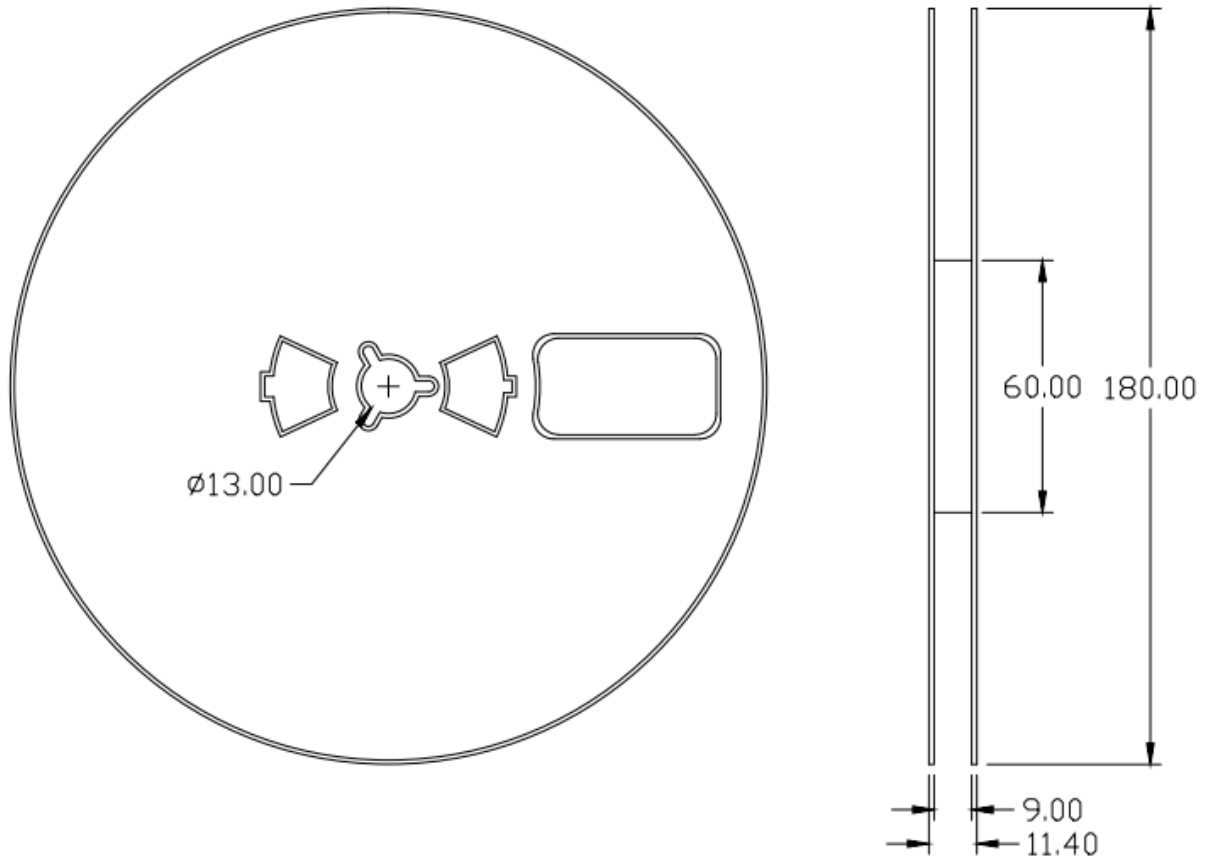


Ordering Information

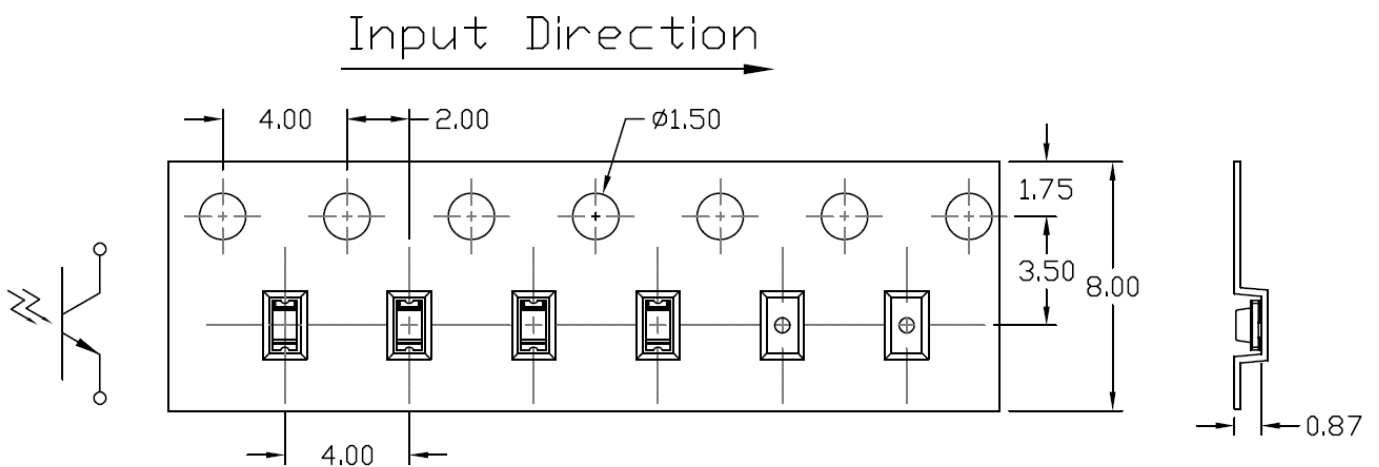
Part Number	Description	Quantity
PTP81608T08	Tape & Reel	4000 pcs



Reel Dimension *All dimensions are in mm, unless otherwise stated*

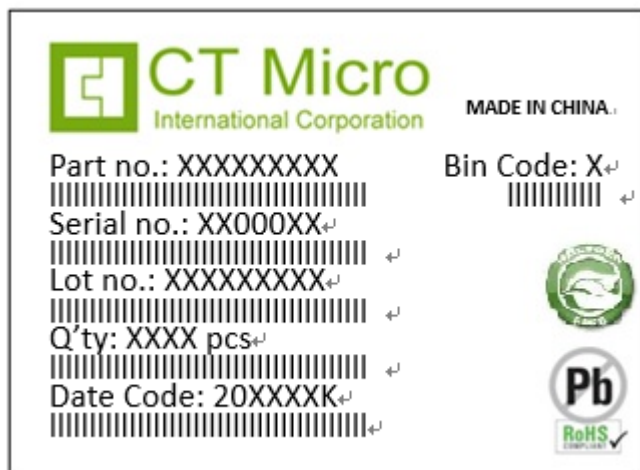


Tape Dimension *All dimensions are in mm, unless otherwise stated*





Label Form Specification



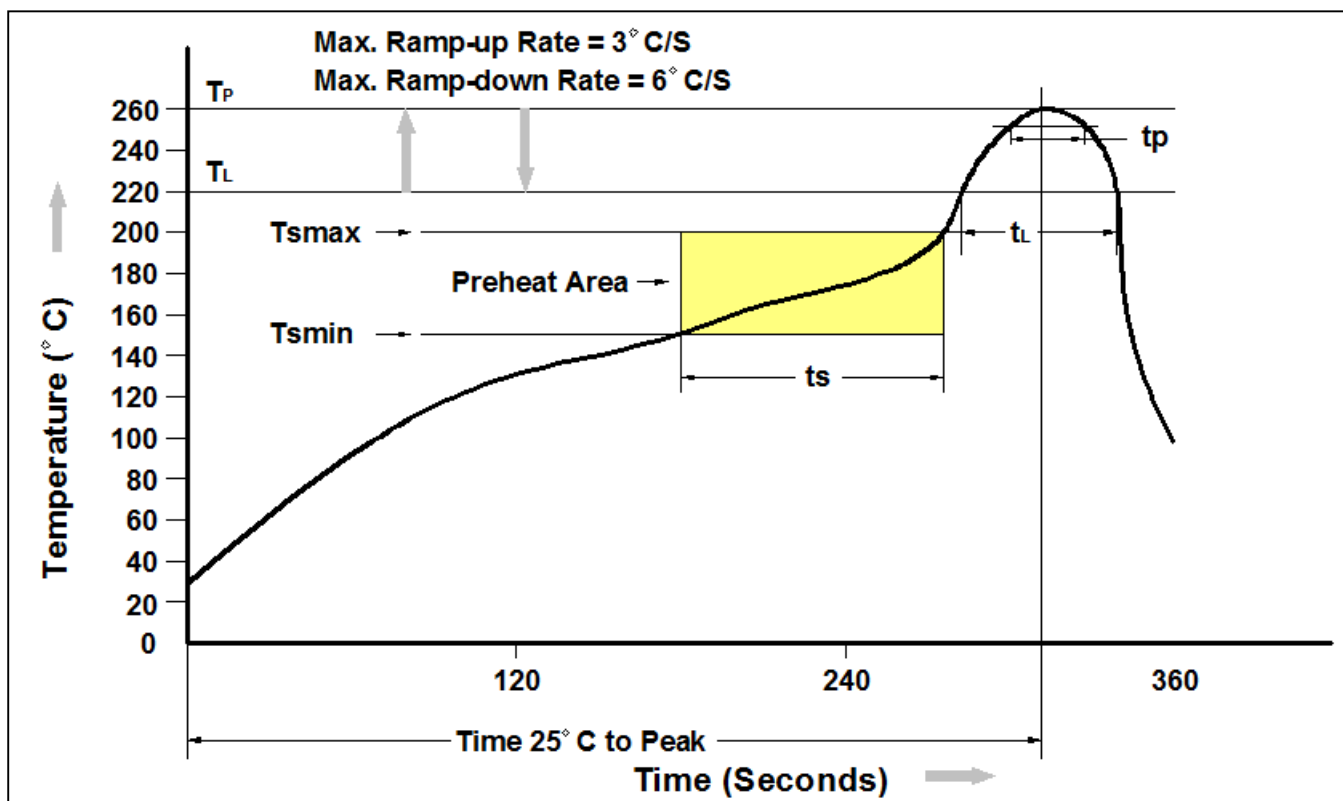
Part no: CTM Production Number
Serial no: Production Number
Lot no: Lot number
Q'ty: Packing Quantity
Date Code: Manufacture Date
Bin Code: Ic Ranks
MADE IN CHINA: Production Place

Storage Condition

1. Do not open moisture proof bag before the products are ready to use.
2. The moisture barrier bag should be stored at 30°C and 90%R.H. max. before opening.
Shelf life of non-opened bag is 12 months after the bag sealing date.
3. After opening the moisture barrier bag floor life is 168h at 30°C/60%RH. max. Unused LEDs should be resealed into moisture barrier bag. (Refer to J-STD-020 Standard)
4. If the moisture absorbent material has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the J-STD-033 Standard conditions.



Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T Amin)	150°C
Temperature Max. (T smax)	200°C
Time (ts) from (T Amin to T smax)	60-120 seconds
Ramp-up Rate (tL to tp)	3°C/second max.
Liquidous Temperature (TL)	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (tp) within 5°C of 260°C	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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